L Number	Hits	Search Text	DB	Time stamp
1	22896	flip near chip	USPAT;	2004/08/20 11:43
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
2	10	(flin many chin) and ((chin dia) with (care many (area marian mant	IBM_TDB	2004/08/20 11:51
2	10	(flip near chip) and ((chip die) with (core near (area region part portion)) with (peripher\$2 near (area region part portion)))	USPAT; US-PGPUB;	2004/08/20 11.31
		portion)) with (peripher 32 hear (area region part portion)))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	57	(flip near chip) and ((chip die) with (core near (area region part	USPAT;	2004/08/20 12:12
Ĭ		portion)))	US-PGPUB;	200 11 00.20 12.12
		po-11-01-///	ЕРО; ЛРО;	
			DERWENT;	
			IBM TDB	
4	7	("5216280" "5512765" "5581109" "5610417" "5641978"	USPAT	2004/08/20 12:00
		"6093942" "6144100").PN.		
5	20		USPAT	2004/08/20 12:05
		"5153507" "5239448" "5258648" "5281151" "5341049"		
		"5381307" "5391917" "5422441" "5490040" "5510758"		
		"5523622" "5545923" "5672911" "5686764" "5703402").PN.		
6		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	USPAT	2004/08/20 12:08
7	1860	((chip die) with (core near (area region part portion)))	USPAT;	2004/08/20 12:16
	. !		US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
	ارا		IBM_TDB	2004/00/20 12:22
8	6	(((chip die) with (core near (area region part portion)))) and (peripher\$2	USPAT; US-PGPUB;	2004/08/20 12:22
		with (electrostatic near discharge (ESD)))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	57	(((chip die) with (core near (area region part portion)))) and	USPAT;	2004/08/20 12:44
		((electrostatic near discharge) ESD)	US-PGPUB;	200 17 00, 20 12, 11
		(((ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
10	6	("5155065" "5300796" "5552333" "5598347" "5754826"	USPAT	2004/08/20 12:32
		"6374203").PN.		
11	6		USPAT	2004/08/20 12:33
		"6374203").PN.		
12	8874	power with ground with (arrang\$5 configur\$6 layout)	USPAT;	2004/08/20 12:46
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
13	332	(flip near chip) and (power with ground with (arrang\$5 configur\$6	USPAT;	2004/08/20 12:59
1.5	332	layout))	US-PGPUB;	230 11 001 20 12.37
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
14	36	((flip near chip) and (power with ground with (arrang\$5 configur\$6	USPAT;	2004/08/20 12:55
		layout))) and ESD	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
15	2	((flip near chip) and (power with ground with (arrang\$5 configur\$6	USPAT;	2004/08/20 12:54
		layout))) and ((under near ball near metallization) UBM)	US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	L

	,		Tran . m	
16	4	(power with ground with (arrang\$5 configur\$6 layout)) and ((under near	USPAT;	2004/08/20 12:55
		ball near metallization) UBM)	US-PGPUB;	
	r		ЕРО; ЈРО;	
			DERWENT;	
		A STORY	IBM_TDB	2004/00/20 12 55
17	504	(flip near chip) and ((under near ball near metallization) UBM)	USPAT;	2004/08/20 12:55
		,	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
1.0	_	((C) 1') 1(() 1 1 1 1 1 1 1 1 1 1	IBM_TDB	2004/00/20 12:00
18	5	((flip near chip) and ((under near ball near metallization) UBM)) and	USPAT;	2004/08/20 13:00
		ESD	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT; IBM TDB	
19	2	((flip near chip) and ((under near ball near metallization) UBM)) and	USPAT;	2004/08/20 12:59
19	2	((inp near clip) and ((under near ban near metallization) OBM)) and (power with ground with (arrang\$5 configur\$6 layout))	US-PGPUB;	2004/06/20 12.39
		(power with ground with (arrangs) configurso layout))	EPO; JPO;	
			DERWENT;	
			IBM TDB	
20	492	((flip near chip) and ((under near ball near metallization) UBM)) and	USPAT;	2004/08/20 13:00
20	472	bump\$1	US-PGPUB;	200 1100/20 15.00
		· ·	EPO; JPO;	
			DERWENT;	
			IBM TDB	
21	425	(((flip near chip) and ((under near ball near metallization) UBM)) and	USPAT;	2004/08/20 13:00
	,,	bump\$1) and connect\$3	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
22	90	(((flip near chip) and ((under near ball near metallization) UBM)) and	USPAT;	2004/08/20 13:01
		bump\$1) and (connect\$3 near (structure circuit device configur\$5))	US-PGPUB;	
		. "	ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	